TECHMAN Electronics





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Meet TECHMAN SSD at the Flash Memory Summit 2017

PC100 with built in 3D NAND flash

for upgraded capacity, performance and reliability

Santa Clara, CA, August 7, 2017 – TECHMAN SSD, a leading manufacturer of flash memory solutions optimizing applications for the enterprise, will be exhibiting its latest memory innovations at the Flash Memory Summit 2017 in Santa Clara, California (August 8-10, 2017). On booth #213 with Microsemi of the Santa Clara Convention Center, TECHMAN SSD will be presenting PC100 NVMe SSD series with next-gen NVMe controller and built-in 3D NAND flash for upgraded capacity, performance, and reliability.

By combining the NVMe protocol and 3D NAND flash technology, the new product- PC100 of TECHMAN SSD significantly optimizes the "performance - power" characteristics and boosts to higher capacity utilizing the latest controllers of Microsemi and Toshiba's brand-new 3D NAND flash. With built-in next generation 3D NAND flash, TECHMAN PC100 NVMe SSD provides an incredible 4K random read performance of up to 470K IOPS with only 10 Watt of power consumption, bringing the great reward to TCO. Moreover, PC100 is estimated to support the highest NVMe storage capacity- 16TB in the future.



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TECHMAN SSD is a leading manufacturer of flash memory solutions optimizing applications for the enterprise. Upon standardized products, TECHMAN SSD has offered full-level feature customization to fulfill customers' architectures. Focusing only on Enterprise NVMe SSDs, we deliver SPEED, SECURE, & SERVICE SSD solutions to customers for the era of Cloud Compute, Big Data, Machine Learning, & Internet of Things.

Media Contact:

Ruochiao.Wang@qsitw.com

Sales Contact:

Robert.Hsiao@tm-ssd.com